



MRT-1052 (07/21/15)
"Pump Speed as a Reference"

Achieving the proper solder wave height is essential for the best soldering results. The best solder wave height may vary depending on board thickness; solder type, nozzle size, component type... Pump speed may change during the production run to maintain the proper solder wave because of different variables such as:

- A. Solder pot cleanliness
- B. Solder pump maintenance
- C. Nozzle cleanliness
- D. Solder level

Therefore, pump speed should be referenced in process documents as a set point with a high–low range and not one absolute setting. (Refer MRT-1014 see below) Because the speed of the solder pump may change through the process to maintain the best solder wave.

EXAMPLE:

Over the course of soldering product, certain pump parts and nozzles can become scaled or clogged restricting solder flow. (Refer MRT-1026 attached below) In order to maintain correct solder dome height the pump speed may be increased throughout the flow of product.

Please see other related documents:

MRT-1014
MRT-1017.2
MRT-1026

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